



MPF16N65

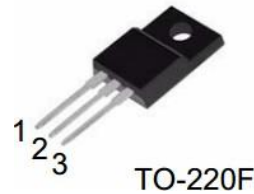
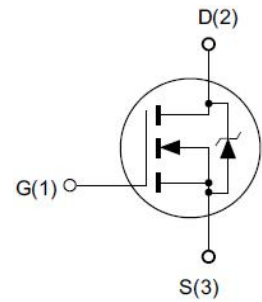
N-Channel Power MOSFET

Features

- ◆ 650V, 16A, $R_{DS(ON)}(Max.) = 0.55\Omega @ V_{GS} = 10V$.
- ◆ Low C_{rss}
- ◆ Fast Switching
- ◆ 100% Avalanche Tested

Application

- ◆ Adapter
- ◆ Standby Power
- ◆ Switching Mode Power Supply



Absolute Maximum Ratings $T_c = 25^\circ C$ unless otherwise noted

| Symbol | Parameter | Limit | Unit |
|----------------|--|------------|------------|
| V_{DS} | Drain-Source Voltage ^a | 650 | V |
| V_{GS} | Gate-Source Voltage | ± 30 | V |
| I_D | Drain Current-Continuous, $T_C = 25^\circ C$ | 16 | A |
| | Drain Current-Continuous, $T_C = 100^\circ C$ | 10.6 | A |
| I_{DM} | Drain Current-Pulsed ^b | 64 | A |
| P_D | Maximum Power Dissipation @ $T_J = 25^\circ C$ | 70 | W |
| EAS | Single Pulsed Avalanche Energy ^d | 605 | mJ |
| T_J, T_{STG} | Operating and Store Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Value | Unit |
|-----------------|---|-------|--------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-Case Max. | 1.79 | $^\circ C/W$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient Max | 100 | $^\circ C/W$ |

Electrical Characteristics $T_J = 25^\circ C$ unless otherwise noted

Off Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|------------|-----------------------------------|---------------------------------|------|------|-----------|---------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | 650 | - | - | |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 650V, V_{GS} = 0V$ | - | - | 1 | μA |
| I_{GSS} | Forward Gate Body Leakage Current | $V_{DS} = 0V, V_{GS} = \pm 30V$ | - | - | ± 100 | nA |



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On Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|--------------|--|-----------------------------------|------|------|------|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2 | - | 4 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance ^c | $V_{GS} = 10V, I_D = 8.0A$ | - | 0.45 | 0.55 | Ω |

Dynamic Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|-----------|---------------------------------------|---|------|------|------|------|
| g_{fs} | Forward Transconductance ^d | $V_{DS} = 15V, I_D = 8.0A$ | | 15 | | S |
| C_{iss} | Input Capacitance | $V_{DS} = 25V,$ $V_{GS} = 0V,$ $f = 1.0MHz$ | - | 2430 | - | pF |
| C_{oss} | Output Capacitance | | - | 215 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 18 | - | pF |

On Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 325V, I_D = 16A,$ $R_G = 25\Omega, V_{GS} = 10V$ | - | 28 | - | ns |
| t_r | Turn-On Rise Time | | - | 68 | - | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | - | 142 | - | ns |
| t_f | Turn-Off Fall Time | | - | 73 | - | ns |
| Q_g | Total Gate Charge | $V_{DS} = 325V, I_D = 16A,$ $V_{GS} = 10V$ | - | 53 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 11 | - | nC |
| Q_{gd} | Gate-Drain Charge | | - | 23 | - | nC |

Drain-Source Diode Characteristics

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|----------|---|--------------------------|------|------|------|------|
| I_S | Drain-Source Diode Forward Continuous Current | $V_{GS} = 0V$ | - | - | 16 | A |
| I_{SM} | Maximum Pulsed Current | $V_{GS} = 0V$ | - | - | 64 | A |
| V_{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0V, I_S = 16A$ | - | 0.9 | 1.4 | V |

Notes:

- $T_J = -55\text{ }^\circ\text{C}$ to $+150\text{ }^\circ\text{C}$
- Repetitive rating; pulse width limited by maximum junction temperature.
- Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$
- $L = 10mH, V_{DD} = 50V, I_{as} = 11.0A, R_G = 25\Omega$ Starting $T_J = 25\text{ }^\circ\text{C}$

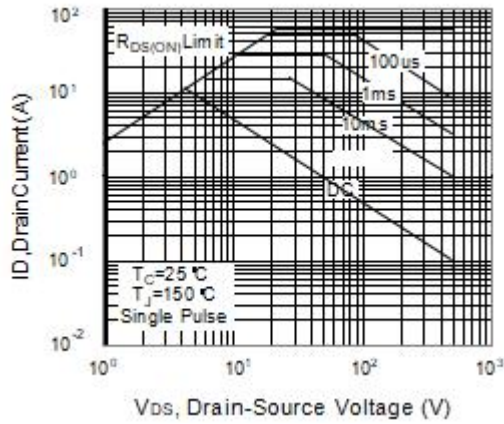


Figure 1 Maximum Safe Operating Area

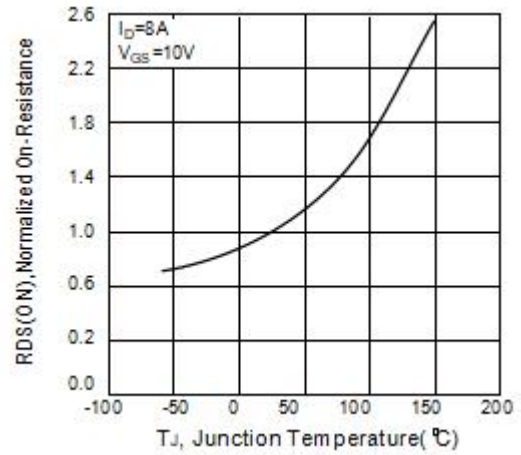


Figure 2 Normalized On-Resistance Variation with Temperature

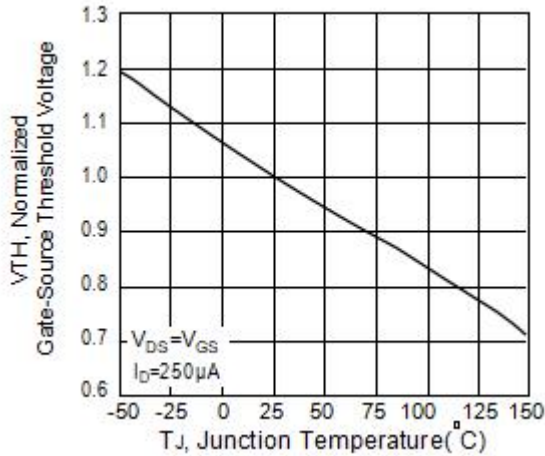


Figure 3. Typical Theshold Voltage vs Junction Temperature

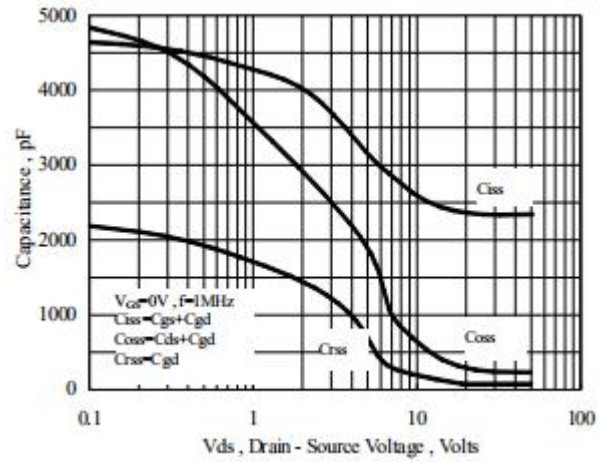


Figure 4. Capacitance Characteristics

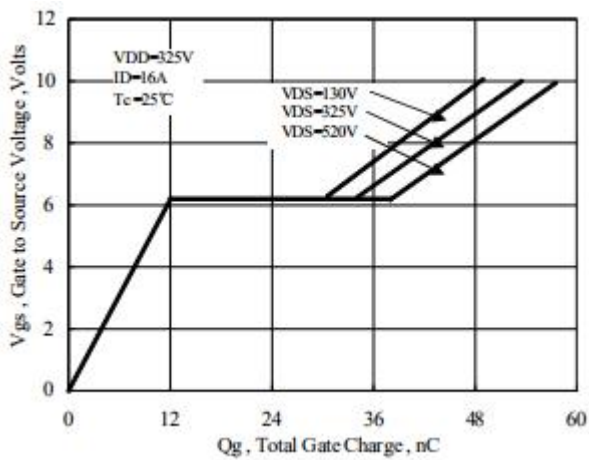


Figure 5. Gate Charge Characteristics

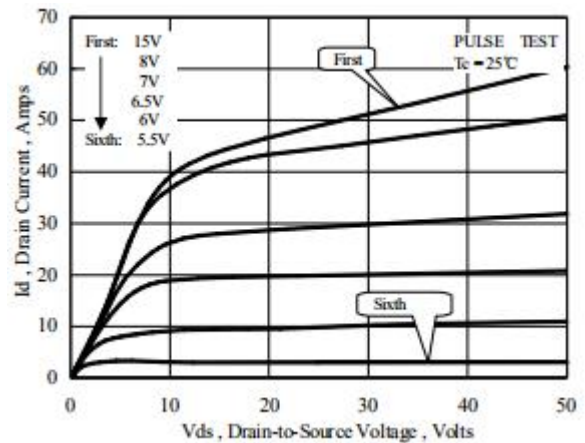


Figure 6. On-State Characteristics

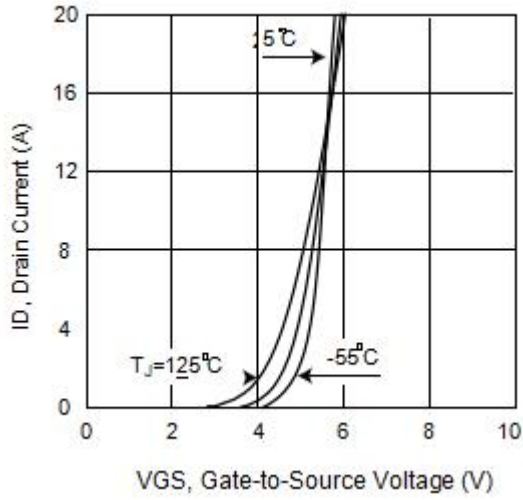


Figure 7. Typical Body Diode Transfer Characteristics

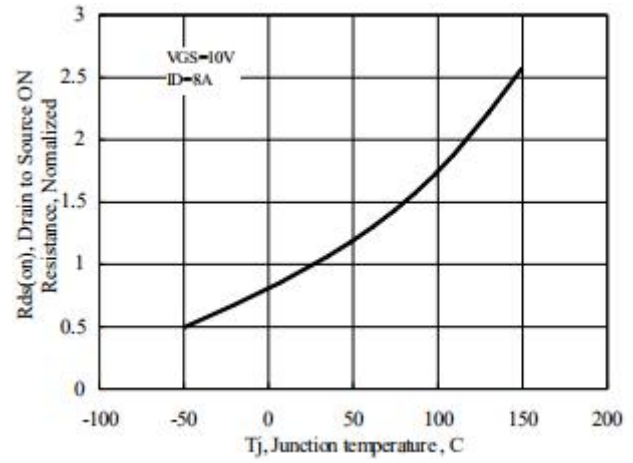


Figure 8. Typical Breakdown Voltage vs Junction Temperature

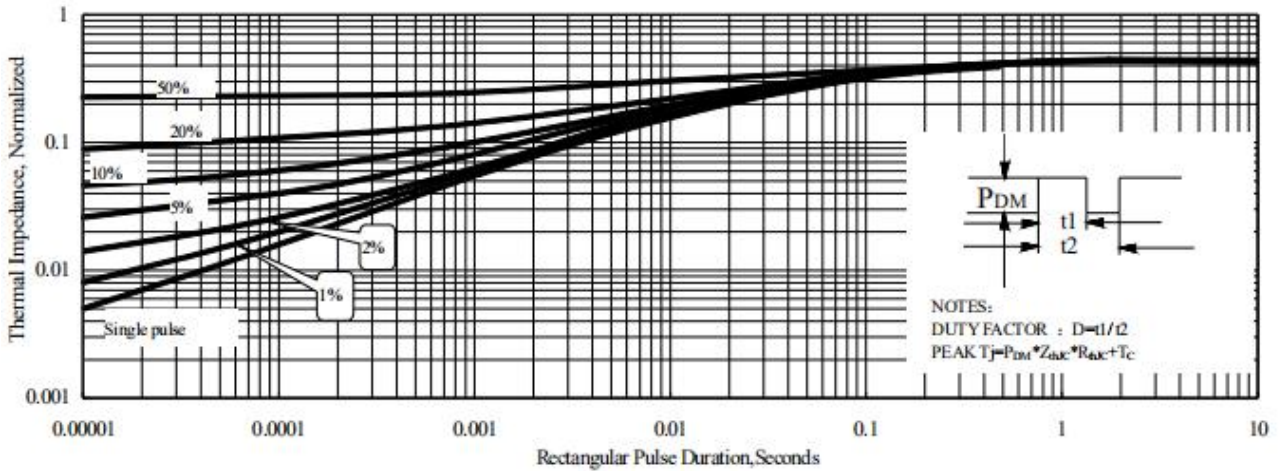


Figure 9. Normalized Effective Transient Thermal Impedance With Pulse Duration(TO-220F)

■ Package Information

